Sensors and Materials

Special Issue on Sensors and Materials in Manufacturing

Call for Papers

First of all, we would like to define what manufacturing is. The term manufacturing refers to the assembly of materials and parts to produce and sell products by manufacturers, and in a broad sense, the related industries. For example, a project for constructing bridge piers on the ground is not classified as manufacturing but construction. However, focusing on piers, sensors that detect the deterioration of piers and maintenance technology to prevent such deterioration are also classified into manufacturing. Thus, manufacturing encompasses a very wide range of technological concepts.

Considering the expertise of the guest editors, papers dealing with the following topics are welcome: sensing technology in the manufacturing of fundamental materials (SOKEIZAI) by plastic forming of mainly metals, by injection molding of mainly plastics, and by casting. In addition, development of new sensors themselves and various maintenance technologies that support the above-mentioned manufacturing are welcome. However, papers on constituent materials themselves that are processed by plastic forming, injection molding, or casting are not welcome.

(I) In more detail, this special first covers a wide range of metal-forming research technologies related to various sensor technologies and sensing systems, including die-embedded sensors, and their applications to process monitoring, process control, and production management technology using online sensing information.

(II) Secondly, it covers a wide range of plastic injection molding and casting technologies related to various sensor technologies and sensing systems, including mold-embedded sensors, and their applications to process monitoring, process control, and production technology using online sensing information.

(III) This special issue covers not only (I) and (II) but also their combination and/or a wide range of related applications including, for example, preventive maintenance via AI technology.

Guest Editors: Professor Ming Yan (Tokyo Metropolitan University) and Professor Masao Murakawa (Nippon Institute of Technology)
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If you have any questions, please feel free to contact the editorial staff at the address below.

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